

ABSTRACT OF THE DISCLOSURE

An [objective of this invention is to provide an] epoxy resin composition for encapsulating a semiconductor chip, which has good flowability without deterioration in curability. Specifically, [this invention provides] a resin composition is disclosed for encapsulating a semiconductor chip containing a phenol aralkyl type epoxy resin containing biphenylene structure(A), a phenol aralkyl type resin containing phenylene or biphenylene structure (B), an inorganic filler (C) and a curing accelerator (D) as main components, [comprising] further containing a silane coupling agent (E) in 0.01 wt% to 1 wt% both inclusive of the total amount of the epoxy resin composition and a Compound (F) [contains] containing two hydroxyl groups combined with each of adjacent carbon atoms [comprising said] on a naphthalene ring in more than or equal to 0.01 wt% of the total amount of the epoxy resin composition.